

Distributed by:

JAMECO[®]
ELECTRONICS

www.Jameco.com ♦ 1-800-831-4242

The content and copyrights of the attached
material are the property of its owner.

Jameco Part Number 800235

FEATURES AND SPECIFICATIONS

Features and Benefits

- Ultra low profile
- Enhanced panel grounding tabs on shielding RJ-45 configuration
- Enclosed top
- Surface Mount Compatible materials
- Pin through paste solderability
- 100% tested for hi-pot and continuity

Reference Information

Product Specification: PSX-43202

Packaging: Tray

UL File No.: E107635

CSA File No.: LR19980

Use with: FCC 68 Plugs

Designed in: Inches

Electrical

Voltage: 125V

Current: 1.5A

Contact Resistance: 10mΩ max.

Dielectric Withstanding Voltage: 1000V AC

Insulation Resistance: 500 MΩ min.

Mechanical Durability: 500 Cycles min.

Physical

Housing: Black glass-filled nylon, UL 94V-0

Contact: Phosphor Bronze

Plating: Contact Area—Post plate 1.27 to 1.52μm (50 to 60μ") Gold

Tail Area—1.90μm (75μ") min. Tin/Lead

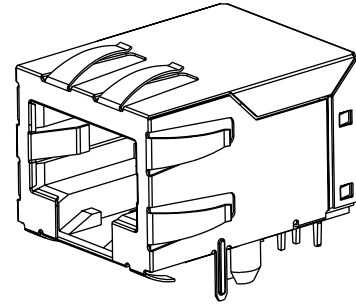
Underplating—Nickel

Operating Temperature: -40 to +85°C

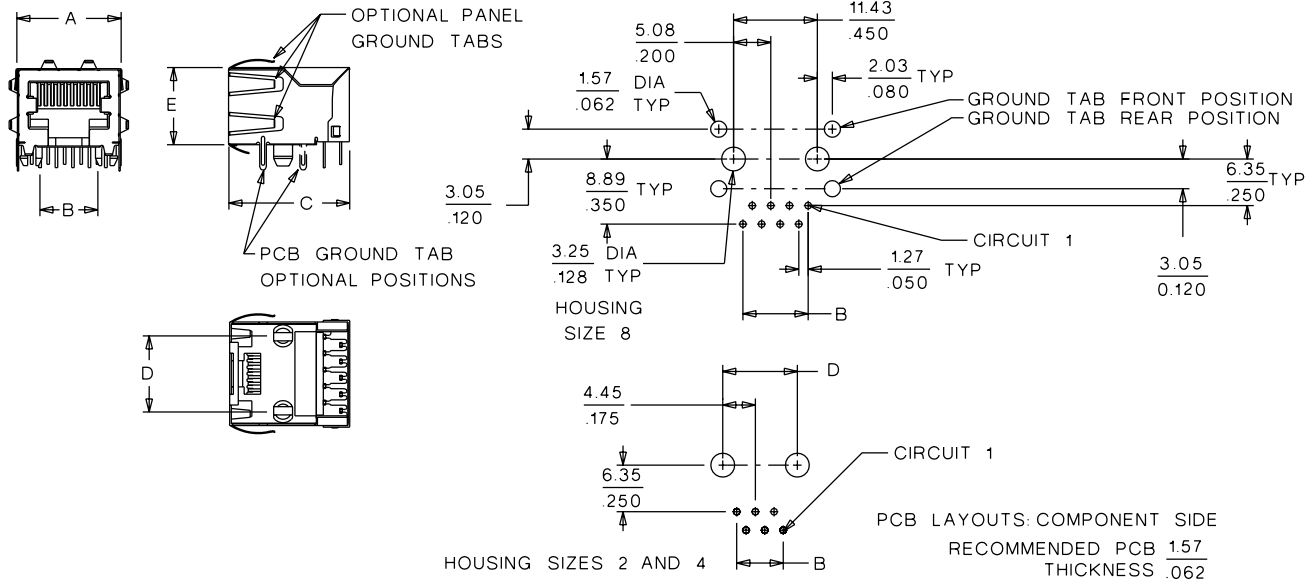
molex® Modular Jack

43202

**Right Angle, Low Profile
Shielded and Unshielded
Versions**



CATALOG DRAWING (FOR REFERENCE ONLY)



ORDERING INFORMATION AND DIMENSIONS

Circuits	Loaded Contacts	Shield Panel Ground Tab Option	Order No.			Dimension				
			Unshielded	Shielded		A	B	C	D	E
				Front Position PCB Ground Tab	Rear Position PCB Ground Tab					
4	2		43202-4104			11.18 (.440)	1.27 (.050)	18.03 (.710)	7.62 (.300)	11.58 (.456)
	4		43202-4101			11.18 (.440)	3.81 (.150)	18.03 (.710)	7.62 (.300)	11.58 (.456)
6	2		43202-6107			13.21 (.520)	1.27 (.050)	18.03 (.710)	10.16 (.400)	11.58 (.456)
	4		43202-6104			13.21 (.520)	3.81 (.150)	18.03 (.710)	10.16 (.400)	11.58 (.456)
	6		43202-6101			13.21 (.520)	6.35 (.250)	18.03 (.710)	10.16 (.400)	11.58 (.456)
8	8		43202-8104			15.24 (.600)	8.89 (.350)	18.03 (.710)	11.43 (.450)	11.58 (.456)
	8	All Panel Ground Tabs	43202-8919	43202-8927		15.85 (.624)	8.89 (.350)	18.39 (.724)	11.43 (.450)	12.09 (.476)
	8	Offset Panel Ground Tabs	43202-8918	43202-8926		15.85 (.624)	8.89 (.350)	18.39 (.724)	11.43 (.450)	12.09 (.476)
	8	Top Panel Ground Tabs	43202-8917	43202-8925		15.85 (.624)	8.89 (.350)	18.39 (.724)	11.43 (.450)	12.09 (.476)
	8	No Panel Ground Tabs	43202-8916	43202-8924		15.85 (.624)	8.89 (.350)	18.39 (.724)	11.43 (.450)	12.09 (.476)
	10		43202-8101			15.24 (.600)	11.43 (.450)	18.03 (.710)	11.43 (.450)	11.58 (.456)
	10	All Panel Ground Tabs	43202-8903	43202-8911		15.85 (.624)	11.43 (.450)	18.39 (.724)	11.43 (.450)	12.09 (.476)
	10	Offset Panel Ground Tabs	43202-8902	43202-8910		15.85 (.624)	11.43 (.450)	18.39 (.724)	11.43 (.450)	12.09 (.476)
	10	Top Panel Ground Tabs	43202-8901	43202-8909		15.85 (.624)	11.43 (.450)	18.39 (.724)	11.43 (.450)	12.09 (.476)
	10	No Panel Ground Tabs	43202-8900	43202-8908		15.85 (.624)	11.43 (.450)	18.39 (.724)	11.43 (.450)	12.09 (.476)



PRODUCT SPECIFICATION

ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACKS

1.0 SCOPE

This Product Specification covers the 1.27 mm (.050 inch) centerline (pitch) printed circuit board (PCB) modular jack connector series with selective gold and tin-lead plating.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND SERIES NUMBER(S)

Ultra Low Profile Right Angle Modular Jacks 43202, 44796

2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate sales drawings (SDA-43202, SDA-44796-001) for information on dimensions, materials, plating and markings.

2.3 SAFETY AGENCY APPROVALS

UL File Number.....E107635

CSA File Number.....LR19980

3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

FCC Rules and Regulations, Part 68, Subpart F

REA Bulletin 345-81, PE-76; Specification for modular telephone set hardware

ANSI/EIA/TIA-568

IEC-60603-7

UL 1863

MIL-STD-202; General requirements for test specifications

4.0 RATINGS

4.1 VOLTAGE

56.5 V DC

150 V_{RMS} AC (Ringing voltage only)

4.2 CURRENT

1.5 Amps @ 25°C

4.3 TEMPERATURE

Operating: - 40°C to + 70°C

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
C	EC No: UCR2004-0250 DATE: 2003/ 08/01	PRODUCT SPECIFICATION ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACKS	1 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43202-001	MKAMAR 01/09/19	MKAMAR 01/09/19	BWIRKUS 01/09/19

TEMPLATE FILENAME: PRODUCT_SPEC[SIZE_A](V.1).DOC



PRODUCT SPECIFICATION

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT
	Contact Resistance (Low Level)	Mate connectors: apply a maximum voltage of 20 mV and a current of 15 mA . (Measurement locations in Section 7.0)	10 milliohms MAXIMUM [initial]
	Insulation Resistance	Unmated connector, mounted to a PCB: apply a voltage of 500 VDC between adjacent terminals and between terminals to ground.	500 Megohms MINIMUM
	Dielectric Withstanding Voltage	Mate connectors: apply a voltage of 1000 VAC for 1 minute between adjacent terminals and between terminals to ground.	No breakdown; current leakage < 5 mA
	Temperature Rise	Mate connectors: measure the temperature rise at the rated current after: 96 hours	Temperature rise; +30°C MAXIMUM

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
C	EC No: UCR2004-0250 DATE: 2003/ 08/01	PRODUCT SPECIFICATION ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACKS	2 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43202-001	MKAMAR 01/09/19	MKAMAR 01/09/19	BWIRKUS 01/09/19



PRODUCT SPECIFICATION

5.2 MECHANICAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT
	Connector Mate Force	Mate connector at a rate of 25 ± 6 mm (1 ± ¼ inch) per minute. (Gage dimensions in Section 7.0)	22 N (5 lbf) MAXIMUM insertion force
	Durability	Mate connectors up to 500 cycles at a maximum rate of 20 cycles per minute prior to Environmental Tests.	10 milliohms MAXIMUM (change from initial)
	Vibration (Random)	Mate connectors and vibrate per MIL-STD-202	10 milliohms MAXIMUM (change from initial) & Discontinuity < 1 microsecond
	Plug Retention Force	Apply an axial pullout force on the plug at a rate of 25 ± 6 mm (1 ± ¼ inch) .	89 N (20 lbf) MINIMUM retention force
	PCB Separation Forces	Apply a perpendicular static load on the plug at a rate of 25 ± 6 mm (1 ± ¼ inch) .	4.5 N (1 lbf) MINIMUM withdrawal force before solder reflow 89 N (20 lbf) MINIMUM withdrawal force after solder reflow

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
C	EC No: UCR2004-0250 DATE: 2003/ 08/01	PRODUCT SPECIFICATION ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACKS	3 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43202-001	MKAMAR 01/09/19	MKAMAR 01/09/19	BWIRKUS 01/09/19

TEMPLATE FILENAME: PRODUCT_SPEC[SIZE_A](V.1).DOC



PRODUCT SPECIFICATION

5.3 ENVIRONMENTAL REQUIREMENTS

	DESCRIPTION	TEST CONDITION	REQUIREMENT												
	Thermal (Cycling)	Connectors to be placed in 95% relative humidity. Maximum temperature change is 15°C/hour. Cycle linearly per chart below. Mate connectors; expose to 10 cycles of: <table><tr><td><u>Temperature °C</u></td><td><u>Duration (Minutes)</u></td></tr><tr><td>30 to 5</td><td>120</td></tr><tr><td>5 to 30</td><td>120</td></tr><tr><td>Hold at 30</td><td>240</td></tr><tr><td>30 to 5</td><td>180</td></tr><tr><td>Hold at 5</td><td>180</td></tr></table>	<u>Temperature °C</u>	<u>Duration (Minutes)</u>	30 to 5	120	5 to 30	120	Hold at 30	240	30 to 5	180	Hold at 5	180	10 milliohms MAXIMUM (change from initial) & Dielectric Withstanding Voltage: No Breakdown at 500 VAC & Insulation Resistance: 500 Megohms MINIMUM & Visual: No Damage
<u>Temperature °C</u>	<u>Duration (Minutes)</u>														
30 to 5	120														
5 to 30	120														
Hold at 30	240														
30 to 5	180														
Hold at 5	180														
	Solderability	Dip solder tails in flux and immerse in solder bath at 230±5°C for 3±0.5 seconds.	Solder Wetting Visual: 95% of immersed area must shown no voids, pin holes												
	Resistance to Soldering Heat	Dip solder tails in molten solder and immerse in solder bath at 260±5°C for 5±0.5 seconds.	Visual: No Damage												

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
C	EC No: UCR2004-0250 DATE: 2003/ 08/01	PRODUCT SPECIFICATION ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACKS	4 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43202-001	MKAMAR 01/09/19	MKAMAR 01/09/19	BWIRKUS 01/09/19

TEMPLATE FILENAME: PRODUCT_SPEC[SIZE_A](V.1).DOC

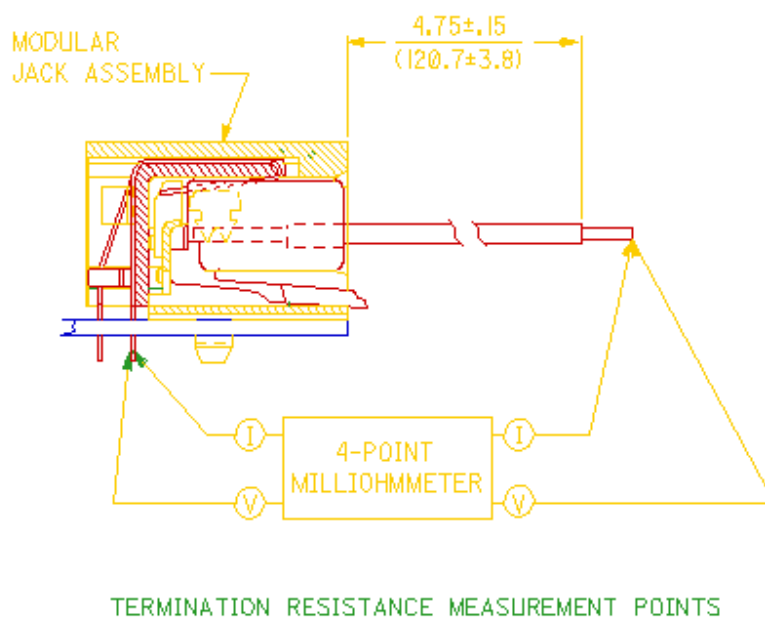


PRODUCT SPECIFICATION

6.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage.
See appropriate sales drawings on Sheet 1 for packaging descriptions.

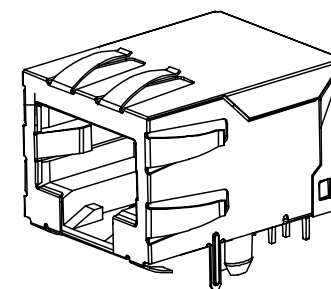
7.0 GAGES AND FIXTURES



8.0 OTHER INFORMATION

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
C	EC No: UCR2004-0250 DATE: 2003/ 08/01	PRODUCT SPECIFICATION ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACKS	5 of 5
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
PS-43202-001	MKAMAR 01/09/19	MKAMAR 01/09/19	BWIRKUS 01/09/19

TEMPLATE FILENAME: PRODUCT_SPEC[SIZE_A](V.1).DOC

SHIELDED MODULAR JACK
SHOWN WITH PANEL GROUND
OPTION 'D' AND FRONT
PCB GROUND TABS.

NOTES:

1) MATERIAL:

HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE SHEETS 5 AND 6
TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
SHIELD: BRASS, .007/(0.18) THICK

2) FINISH:

TERMINALS:

- A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES MIN.
B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES MIN.
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
IN THE PC TAILS AND/OR SHIELD.

SHIELD:

100 MICROINCHES NICKEL OVER 50 MICROINCHES COPPER UNDERPLATE
PCB GROUND TABS DIPPED IN TIN

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43202.

4) PACKAGING SPECIFICATION:

UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43249-004.
UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES
PER MOLEX PACKAGING SPECIFICATION PK-43202-005.
SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43202-004.

5) SEE SHEETS 7 - 9 FOR P.C. BOARD LAYOUTS.

6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.

DRAWING LEGEND

SHEET 1- NOTES, DRAWING LEGEND
SHEET 2- SHIELDED MODULAR JACK W/ BOTTOM GROUND TABS
SHEET 3- SHIELDED MODULAR JACK W/O BOTTOM GROUND TABS
SHEET 4- UNSHIELDED MODULAR JACK
SHEET 5- PART NUMBER CHARTS
SHEET 6- PART NUMBER CHARTS
SHEET 7- FOOTPRINT LAYOUT FOR 4 POSITION HOUSING
SHEET 8- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING
SHEET 9- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING

9	L2
8	L2
7	L2
6	L
5	L
4	K2
3	L1
2	L1
1	L2
SH	REV

ADDED PCB THICKNESS EC NO: UCP2005-2739 DRAWNLSCHMDT 2005/06/20 CHKD: 2005/06/22 APPR: F SMITH 2005/06/23 L2	QUALITY SYMBOLS ▽ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± .014 1 PLACE ± 0.36 ± --- ANGULAR ± 1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SCALE 4:1 DESIGN UNITS INCH DIMENSION STYLE IN/MM DRAWN BY DATE JTR 1993/03/31 CHECKED BY DATE JTR 1993/03/31 APPROVED BY DATE RAS 1993/03/31	THIRD ANGLE PROJECTION REVISE ON CAD ONLY TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY moLEX MOLEX INCORPORATED MATERIAL NO. DOCUMENT NO. SEE SHTS 5&6 SDA-43202 SHEET NO. 1 OF 9	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

13

12

11

10

9

8

7

6

5

4

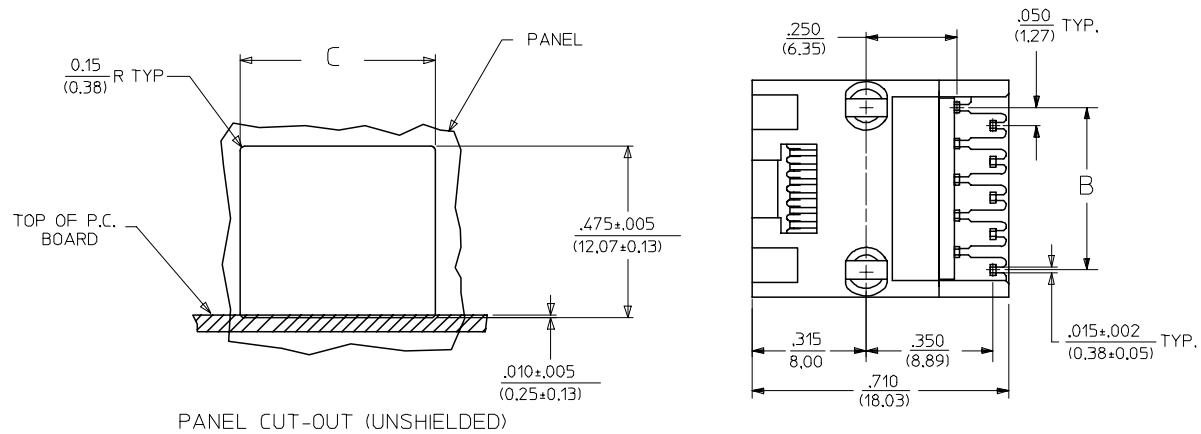
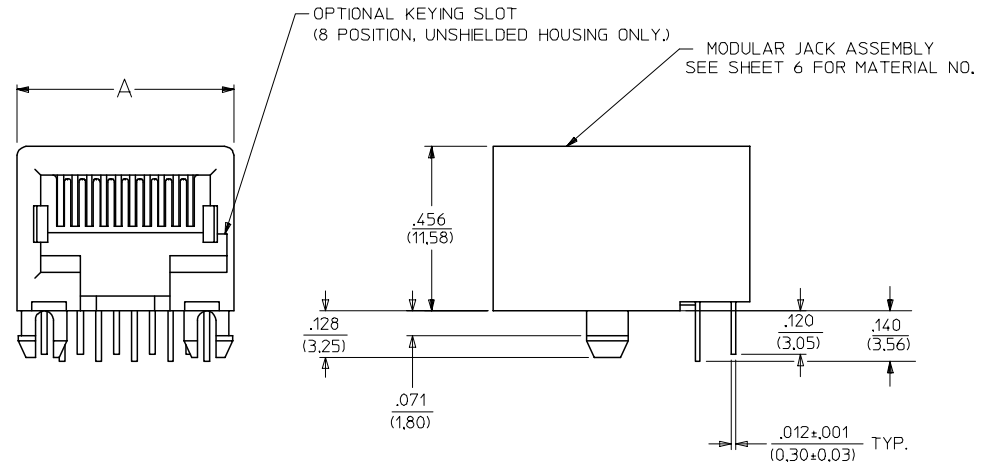
3

2

43202

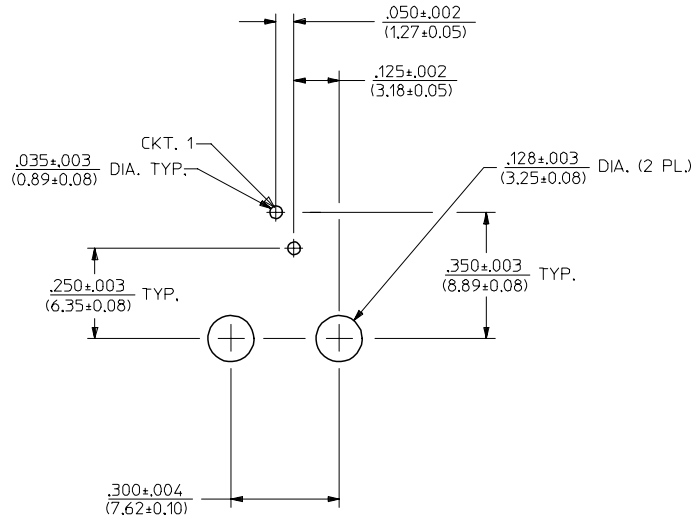
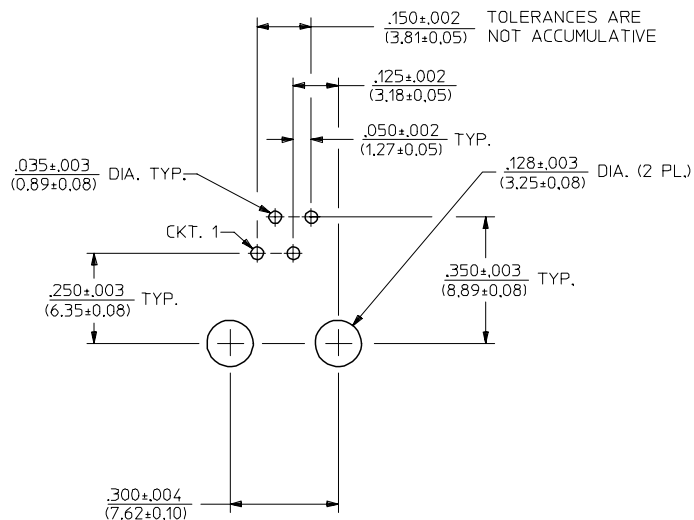
UNSHIELDED MODULAR JACKS

SIZE 8, LOADED 10 SHOWN



HOUSING SIZE	LOADED CIRCUITS	A	B	C
4	4	.440 (11.18)	.150±.005 (3.81±0.13)	.460±.005 (11.68±0.13)
4	2	.440 (11.18)	.050±.005 (1.27±0.13)	.460±.005 (11.68±0.13)
6	6	.520 (13.21)	.250±.005 (6.35±0.13)	.540±.005 (13.72±0.13)
6	4	.520 (13.21)	.150±.005 (3.81±0.13)	.540±.005 (13.72±0.13)
6	2	.520 (13.21)	.050±.005 (1.27±0.13)	.540±.005 (13.72±0.13)
8	10	.600 (15.24)	.450±.005 (11.43±0.13)	.620±.005 (15.75±0.13)
8	8	.600 (15.24)	.350±.005 (8.89±0.13)	.620±.005 (15.75±0.13)
8	6	.600 (15.24)	.250±.005 (6.35±0.13)	.620±.005 (15.75±0.13)
8	4	.600 (15.24)	.150±.005 (3.81±0.13)	.620±.005 (15.75±0.13)
8	2	.600 (15.24)	.050±.005 (1.27±0.13)	.620±.005 (15.75±0.13)

SEE SHEET ONE EC NO: UCP2004-1194 DRAWN:LSCHMDT 2004/01/02 CHKD:LSCHMDT 2004/01/05 APPR:FSMITH 2004/01/09 K2	DESCRIPTION	QUALITY SYMBOLS ▽ = 0 ◻ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY		
					DIMENSION STYLE IN/MM		TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY			
			4 PLACES	± ---	± ---	DRAWN BY JTR	DATE 1993/03/31	MOLEX MOLEX INCORPORATED		
			3 PLACES	± ---	± .010					
			2 PLACES	± 0.25	± .014	CHECKED BY JTR	DATE 1993/03/31	MATERIAL NO. DOCUMENT NO. SHEET NO.		
			1 PLACE	± 0.36	± ---					
			ANGULAR ±1/2°				SEE SHT 6 SDA-43202 4 OF 9			
			DRAFT WHERE APPLICABLE		APPROVED BY RAS					DATE 1993/03/31
			MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

ADD PCB THICKNESS EC NO: UCP2005-2739 DRWN:LSCHMDT 2005/06/20 CHKD:ELHAG 2005/06/22 APPR:FSMITH 2005/06/23 L2	QUALITY SYMBOLS ▽ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± .014 1 PLACE ± 0.36 ± --- ANGULAR ± 1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SCALE 4:1 DESIGN UNITS INCH DIMENSION STYLE IN/MM DRAWN BY JTR DATE 1993/03/31 CHECKED BY JTR DATE 1993/03/31 APPROVED BY RAS DATE 1993/03/31	THIRD ANGLE PROJECTION REVISE ON CAD ONLY TITLE ULTRA LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY moLEX MOLEX INCORPORATED MATERIAL NO. SEE SHT 6 DOCUMENT NO. SDA-43202 SHEET NO. 7 OF 9